

# SOT684-2

plastic thermal enhanced very thin quad flat package; no leads; 56 terminals; body 8 x 8 x 0.85 mm

8 February 2016

Package information

## 1. Package summary

|                                       |  |
|---------------------------------------|--|
| <b>Terminal position code</b>         | Q (quad)   |
| <b>Package type descriptive code</b>  | HVQFN56  |
| <b>Package type industry code</b>     | HVQFN56  |
| <b>Package style descriptive code</b> | HVQFN (thermal enhanced very thin quad flatpack; no leads) |
| <b>Package style suffix code</b>      | NA (not applicable)  |
| <b>Package body material type</b>     | P (plastic)  |
| <b>JEDEC package outline code</b>     | MO-220   |
| <b>Mounting method type</b>           | S (surface mount)  |
| <b>Issue date</b>                     | 22-10-2002   |

Table 1. Package summary

| Symbol         | Parameter                      | Min   | Typ | Nom  | Max   | Unit |
|----------------|--------------------------------|-------|-----|------|-------|------|
| D              | package length                 | 7.9   | -   | 8    | 8.1   | mm   |
| E              | package width                  | 7.9   | -   | 8    | 8.1   | mm   |
| A              | seated height                  | 0.8   | -   | 0.85 | 1     | mm   |
| A <sub>2</sub> | package height                 | [tbd] | -   | 0.85 | [tbd] | mm   |
| e              | nominal pitch                  | -     | -   | 0.5  | -     | mm   |
| n <sub>2</sub> | actual quantity of termination | -     | -   | 56   | -     |      |

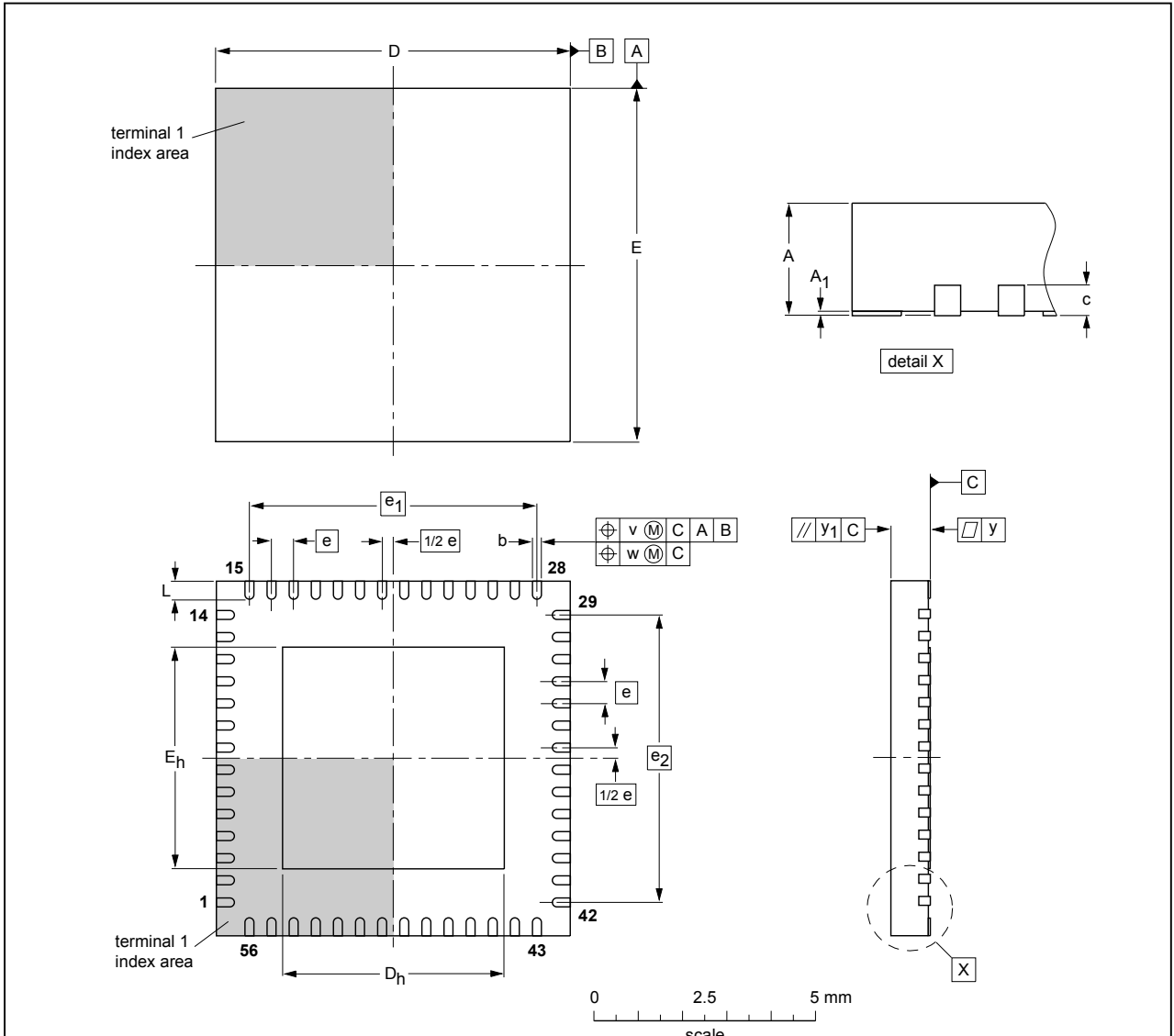


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## 2. Package outline

HVQFN56: plastic thermal enhanced very thin quad flat package; no leads; 56 terminals; body 8 x 8 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

| UNIT | A <sup>(1)</sup> max. | A <sub>1</sub> | b            | c   | D <sup>(1)</sup> | D <sub>h</sub> | E <sup>(1)</sup> | E <sub>h</sub> | e   | e <sub>1</sub> | e <sub>2</sub> | L          | v   | w    | y    | y <sub>1</sub> |
|------|-----------------------|----------------|--------------|-----|------------------|----------------|------------------|----------------|-----|----------------|----------------|------------|-----|------|------|----------------|
| mm   | 1                     | 0.05<br>0.00   | 0.30<br>0.18 | 0.2 | 8.1<br>7.9       | 5.35<br>5.05   | 8.1<br>7.9       | 5.35<br>5.05   | 0.5 | 6.5            | 6.5            | 0.5<br>0.3 | 0.1 | 0.05 | 0.05 | 0.1            |

**Note**

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

| OUTLINE VERSION | REFERENCES |        |       |  | EUROPEAN PROJECTION | ISSUE DATE            |
|-----------------|------------|--------|-------|--|---------------------|-----------------------|
|                 | IEC        | JEDEC  | JEITA |  |                     |                       |
| SOT684-2        | ---        | MO-220 | ---   |  |                     | -02-04-24<br>02-10-22 |

Fig. 1. Package outline HVQFN56 (SOT684-2)

plastic thermal enhanced very thin quad flat package; no leads; 56 terminals; body 8 x 8 x 0.85 mm

### 3. Soldering

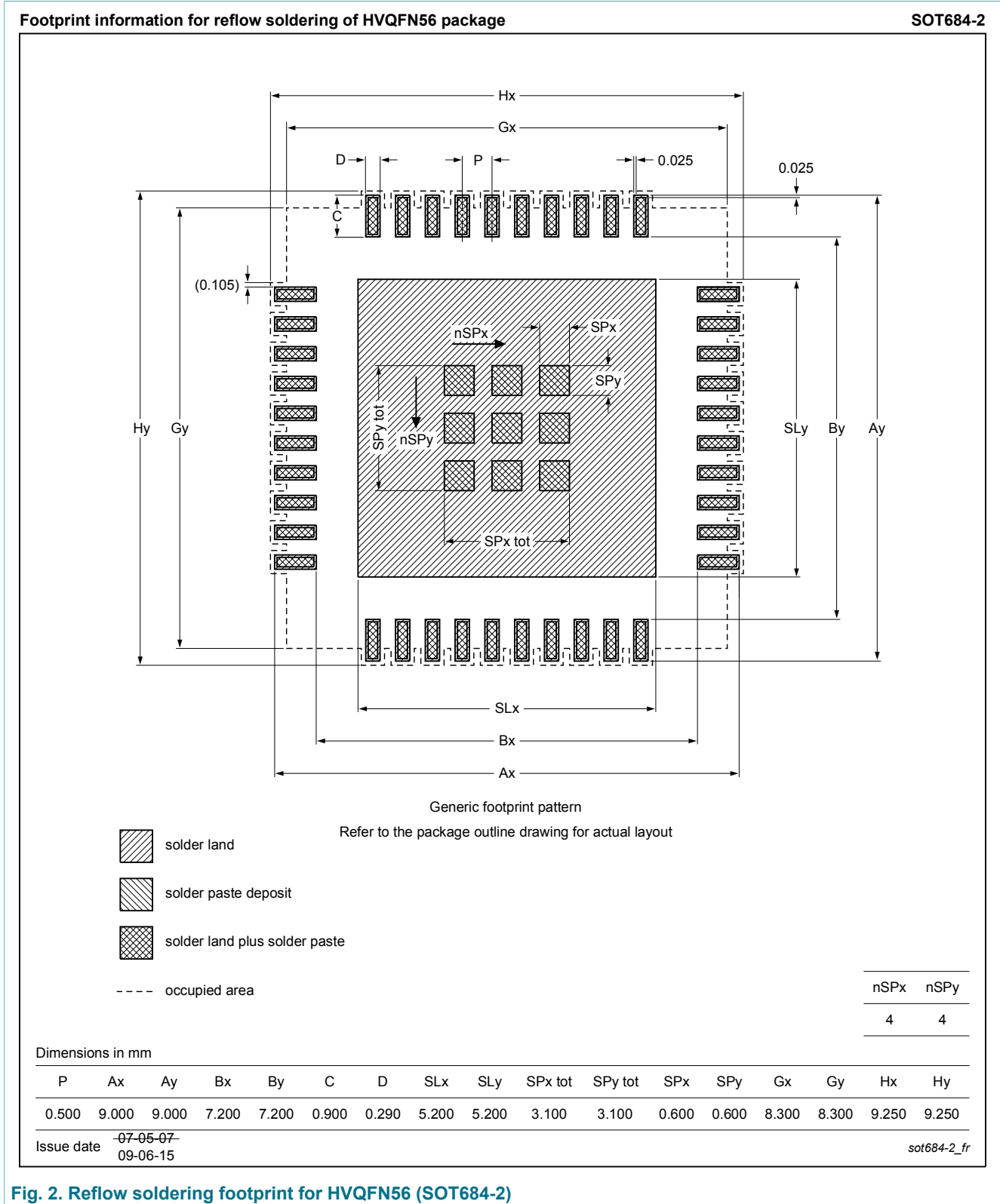


Fig. 2. Reflow soldering footprint for HVQFN56 (SOT684-2)

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## 4. Legal information

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Date of release: 8 February 2016

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